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ICS 77.150.01
CCS H68

YS

NONFERROUS METALS INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

YS/T 1850-2026

Bonding wire base material for semiconductor packaging

半导体封装用键合丝母材

(English Translation)

Issued on: April 15, 2026 **Implemented on: November 1, 2026**

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Foreword

YS/T 1850-2026 is a recommended industry standard of the People's Republic of China in the Nonferrous Metals sector, approved and issued by the Ministry of Industry and Information Technology on 15 April 2026, with effect from 1 November 2026.

Classification: ICS 77.150.01; CCS H68.

1 Scope

YS/T 1850-2026 specifies the classification and designation, technical requirements, test methods, inspection rules, marking, packaging, transport, storage, accompanying documents and order form content for the base material used to make bonding wire for semiconductor packaging. It applies to the base material used for semiconductor packaging bonding wire. The base material is the metal from which bonding wire is later drawn, so the requirements concern the material supplied to the wire maker rather than the finished bonding wire.

Producers of bonding wire base material, bonding wire manufacturers, semiconductor packaging companies and testing laboratories can use it. It is a voluntary standard (code with /T), issued by the Ministry of Industry and Information Technology on 15 April 2026 and effective from 1 November 2026. It is a new standard.

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